

SN54S140, SN74S140 DUAL 4-INPUT POSITIVE-NAND 50-OHM LINE DRIVERS

SDLS210 – DECEMBER 1983 – REVISED MARCH 1988

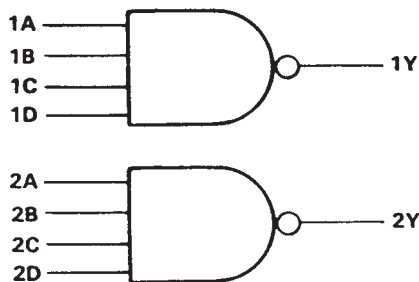
- Package Options Include Ceramic Chip Carriers and Flat Packages in Addition to Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

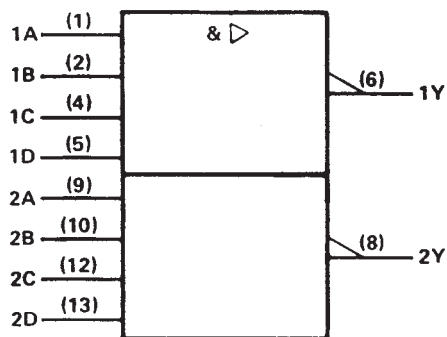
These devices contain two independent 4-input positive-NAND 50-ohm line drivers. They perform the Boolean function $Y = \overline{ABCD}$.

The SN54S140 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74S140 is characterized for operation from 0°C to 70°C .

logic diagram (each driver)



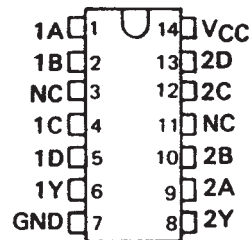
logic symbol†



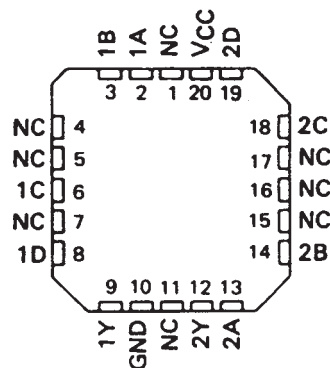
† This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN54S140 . . . J OR W PACKAGE
SN74S140 . . . D OR N PACKAGE
(TOP VIEW)



SN54S140 . . . FK PACKAGE
(TOP VIEW)

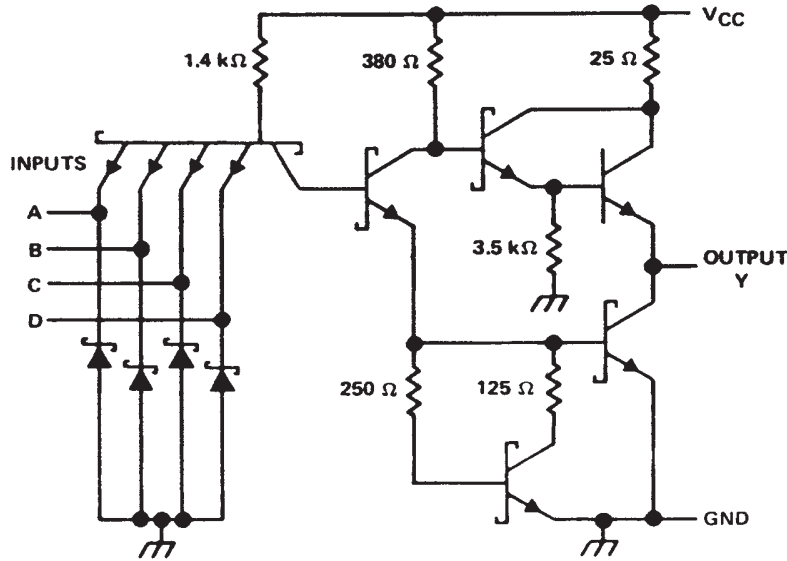


NC—No internal connection

SN54S140, SN74S140 DUAL 4-INPUT POSITIVE-NAND 50-OHM LINE DRIVERS

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schematic (each driver)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	5.5 V
Operating free-air temperature range: SN54'	-55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

SN54S140, SN74S140

DUAL 4-INPUT POSITIVE-NAND 50-OHM LINE DRIVERS

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recommended operating conditions

	SN54S140			SN74S140			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage	0.8			0.8			V
I _{OH} High-level output current	-40			-40			mA
I _{OL} Low-level output current	60			60			mA
T _A Operating free-air temperature	-55 125			0 70			°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54S140			SN74S140			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V _{IK}	V _{CC} = MIN, I _I = -18 mA	-1.2			-1.2			V
V _{OH}	V _{CC} = MIN, V _{IL} = 0.8 V, I _{OH} = -3 mA	2.5	3.4		2.7	3.4		V
	V _{CC} = MIN, V _{IL} = 0.5 V, R _O = 50 Ω to GND	2			2			
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 60 mA	0.5			0.5			V
I _I	V _{CC} = MAX, V _I = 5.5 V	1			1			mA
I _{IH}	V _{CC} = MAX, V _{IH} = 2.7 V	0.1			0.1			mA
I _{IL}	V _{CC} = MAX, V _{IL} = 0.5 V	-4			-4			mA
I _{OS} §	V _{CC} = MAX	-50	-225		-50	-225		mA
I _{CCH}	V _{CC} = MAX, V _I = 0 V	10 18			10 18			mA
I _{CCL}	V _{CC} = MAX, V _I = 4.5 V	25 44			25 44			mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed 100 milliseconds.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t _{PLH}	Any	Y	R _L = 93 Ω,	C _L = 50 pF	4	6.5		ns
t _{PHL}					4	6.5		ns
t _{PLH}			R _L = 93 Ω,	C _L = 150 pF	6			ns
t _{PHL}					6			ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
JM38510/08101BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/08101BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/08101BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN54S140J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54S140J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN74S140D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S140N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S140N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S140N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S140NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S140NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S140NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
SN74S140NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54S140FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S140FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S140J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54S140J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54S140W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S140W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

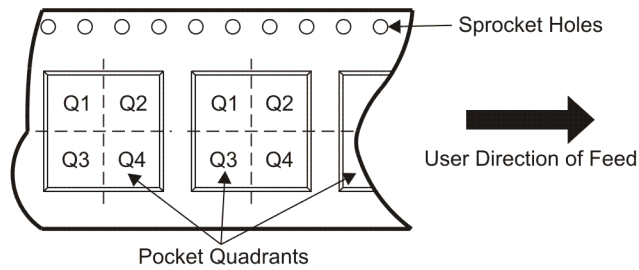
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TAPE AND REEL INFORMATION



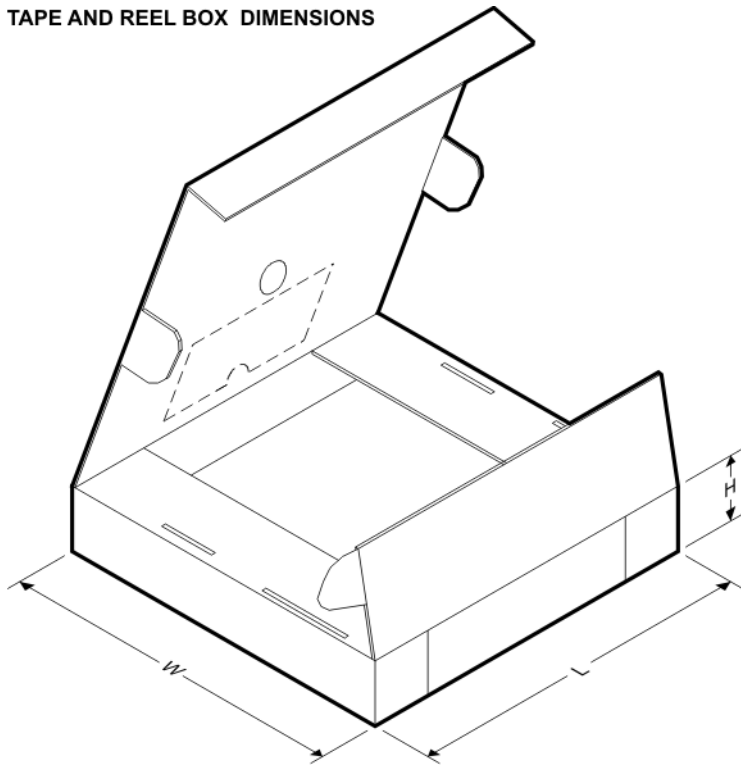
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74S140DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74S140NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74S140DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74S140NSR	SO	NS	14	2000	346.0	346.0	33.0

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

D (R-PDSO-G14)

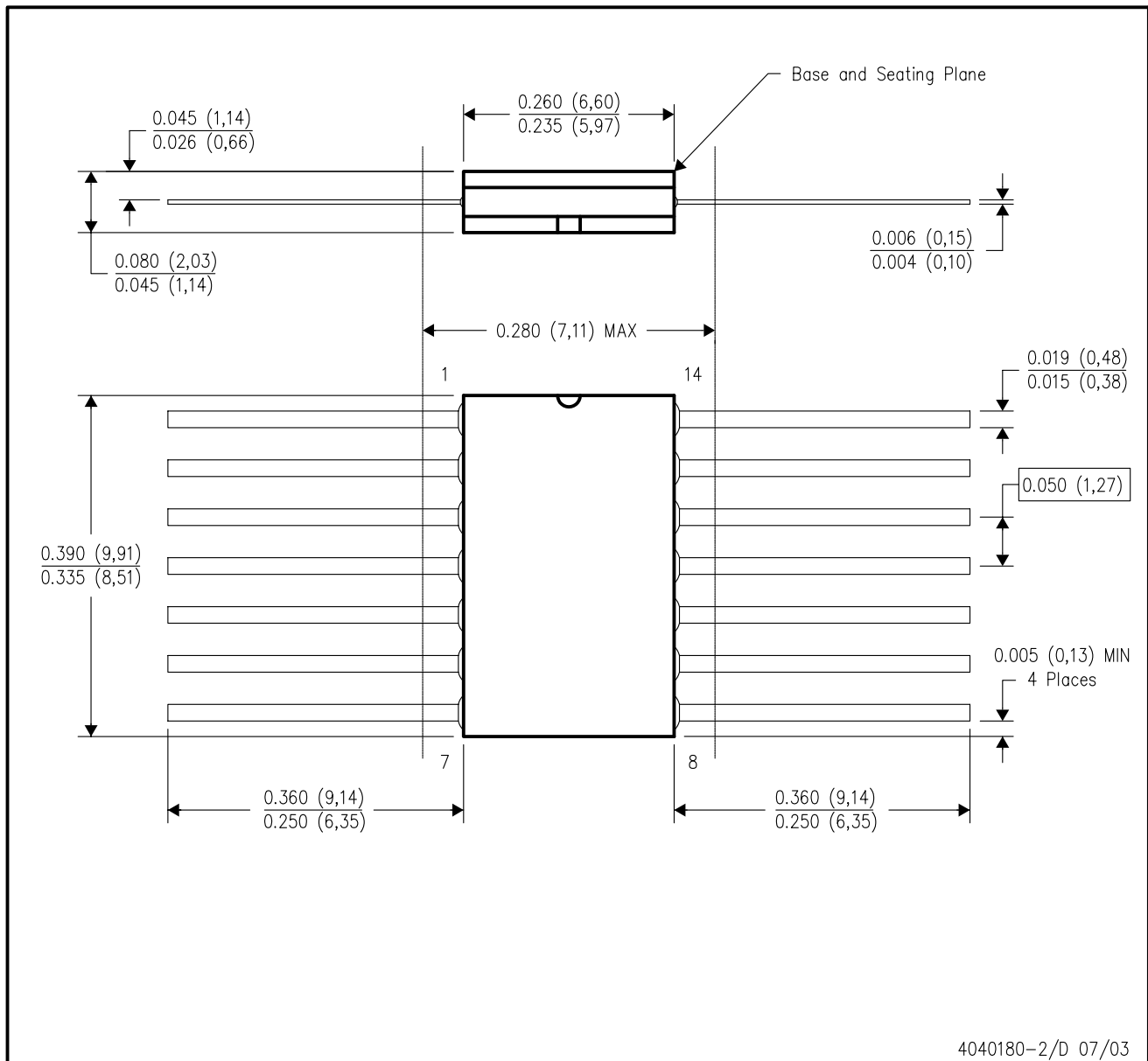
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AB.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

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